



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

<p>In re application of:</p> <p>Basol et al.</p> <p>Serial No.: 10/723,045</p> <p>Filed: November 26, 2003</p> <p>Title: Electrode Assembly For Electrochemical Processing Of Workpiece</p>	<p>Group Art Unit: 1742</p> <p>Examiner:</p> <p>Docket: NT-285-US</p>
---	---

INFORMATION DISCLOSURE STATEMENT

US PATENT DOCUMENTS

Examiner Initials	Cite No.	Document Number	Publication Date	Name of Patentee or Applicant	
NS	AA	6,365,017	April, 2002	Hongo et al.	In Serial No. 09/845,262
NS	AB	2001/0041526	Nov., 2001	Perlov et al.	In Serial No. 09/845,262
NS	AC	6,299,741	Oct., 2001	Sun et al.	In Serial No. 09/845,262
NS	AD	6,297,155	Oct., 2001	Simpson et al.	In Serial No. 09/845,262
NS	AE	2001/0017258	Aug., 2001	Ishida et al.	In Serial No. 09/845,262
NS	AD	6,261,433	July, 2001	Landau	In Serial No. 09/845,262
NS	AF	6,261,426	July, 2001	Uzoh et al.	In Serial No. 09/760,757
NS	AG	6,244,942	June, 2001	Zuniga	In Serial No. 09/845,262
NS	AH	6,193,859	Feb., 2001	Contolini et al.	In Serial No. 09/845,262
NS	AI	6,176,992	Jan., 2001	Talieh	In Serial No. 09/845,262
NS	AJ	6,162,344	Dec., 2000	Reid et al.	In Serial No. 09/760,757
NS	AK	6,159,354	Dec., 2000	Contolini et al.	In Serial No. 09/760,757
NS	AL	6,156,167	Dec., 2000	Patton et al.	In Serial No. 09/760,757
NS	AM	6,136,163	Oct., 2000	Cheung et al.	In Serial No. 09/845,262
NS	AN	6,132,587	Oct., 2000	Jorne et al.	In Serial No. 09/845,262
NS	AO	6,113,759	Sep., 2000	Uzoh	In Serial No. 09/845,262
NS	AP	6,106,378	Aug., 2000	Perlov et al.	In Serial No. 09/845,262
NS	AQ	6,103,085	Aug., 2000	Woo et al.	In Serial No. 09/845,262
NS	AR	6,074,544	June, 2000	Reid et al.	In Serial No. 09/845,262
NS	AS	6,071,388	June, 2000	Uzoh	In Serial No. 09/845,262
NS	AT	6,066,030	May, 2000	Uzoh	In Serial No. 09/845,262
NS	AU	6,063,506	May, 2000	Andricacos et al.	In Serial No. 09/845,262
NS	AV	6,027,631	Feb., 2000	Broadbent	In Serial No. 09/845,262
NS	AW	6,017,437	Jan., 2000	Ting et al.	In Serial No. 09/568,584
NS	AX	6,004,880	Dec., 1999	Liu et al.	In Serial No. 09/845,262
NS	AY	6,001,235	Dec., 1999	Arken et al.	In Serial No. 09/760,757
NS	AZ	5,985,123	Nov., 1999	Koon	In Serial No. 09/845,262
NS	BA	5,946,331	Nov., 1999	Chang et al.	In Serial No. 09/760,757
NS	BB	5,954,997	Sep., 1999	Kaufman et al.	In Serial No. 09/845,262
NS	BC	5,933,753	Aug., 1999	Simon et al.	In Serial No. 09/845,262
NS	BD	5,930,669	July, 1999	Uzoh	In Serial No. 09/845,262
NS	BE	5,922,091	July, 1999	Tsai et al.	In Serial No. 09/845,262
NS	BF	5,911,619	June, 1999	Uzoh et al.	In Serial No. 09/845,262

NS	BG	5,897,375	April, 1999	Watts et al.	In Serial No. 09/845,262
NS	BH	5,884,990	Mar., 1999	Burghartz et al.	In Serial No. 09/845,262
NS	BI	5,858,813	Jan., 1999	Scherber et al.	In Serial No. 09/845,262
NS	BJ	5,840,629	Nov., 1998	Carpio	In Serial No. 09/845,262
NS	BK	5,807,165	Sep., 1998	Uzoh et al.	In Serial No. 09/845,262
NS	BL	5,795,215	Aug., 1998	Guthrie et al.	In Serial No. 09/845,262
NS	BM	5,793,272	Aug., 1998	Burghartz et al.	In Serial No. 09/845,262
NS	BN	5,773,364	June, 1998	Farkas et al.	In Serial No. 09/845,262
NS	BO	5,770,095	June, 1998	Sasaki et al.	In Serial No. 09/845,262
NS	BP	5,762,544	June, 1998	Zuniga et al.	In Serial No. 09/845,262
NS	BQ	5,755,859	May, 1998	Brusic et al.	In Serial No. 09/845,262
NS	BR	5,683,564	Nov., 1997	Reynolds	In Serial No. 09/845,262
NS	BS	5,681,215	Oct., 1997	Sherwood et al.	In Serial No. 09/845,262
NS	BT	5,516,412	May, 1996	Andricacos et al.	In Serial No. 09/845,262
NS	BU	5,354,490	Oct., 1994	Yu et al.	In Serial No. 09/845,262
NS	BV	5,256,565	Oct., 1993	Bernhardt et al.	In Serial No. 09/845,262
NS	BW	5,084,071	Jan., 1992	Nenadic et al.	In Serial No. 09/845,262
NS	BX	4,975,159	Dec., 1990	Dahms	In Serial No. 09/845,262
NS	BY	4,954,142	Sep., 1990	Carr et al.	In Serial No. 09/845,262
NS	BZ	4,948,474	Aug., 1990	Miljkovic	In Serial No. 09/845,262
NS	CA	4,430,173	Feb., 1984	Boudot et al.	In Serial No. 09/845,262
NS	CB	4,258,316	Mar., 1981	Leif	In Serial No. 09/845,262
NS	CC	3,328,273	June, 1967	Creutz et al.	In Serial No. 09/845,262

FOREIGN PATENT DOCUMENTS

Examiner Initials	Cite No.	Document Number	Publication Date	Name of Patentee or Applicant		
NS	CD	WO 98/27585	June, 1998	Deligianni et al.	In Serial No. 09/845,262	
NS	CE	WO 00/26443	May, 2000	Talieh	In Serial No. 09/845,262	

OTHER DOCUMENTS

Examiner Initials	Cite No.			Translation
NS	CF	James J. Kelly et al., "Leveling and Microstructural Effects of Additives for Copper Electrodeposition", Journal of the Electrochemical Society, 146 (7), 1999, pp.2540-2545.	In Serial No. 09/845,262	
NS	CG	Joseph M. Steigerwald et al., "Chemical Mechanical Planarization of Microelectronic Materials", A Wiley-Interscience Publication, 1997, by John Wiley & Sons, Inc. pp.212-222	In Serial No. 09/845,262	
NS	CH	Robert D. Mikkola et al. "Investigation of the Roles of the Additive Components for Second Generation Copper Electroplating Chemistries Used for Advanced Interconnect Metalization", 2000 IEEE, IEEE Electron Devices Society, pp. 117-119	In Serial No. 09/845,262	

Examiner Signature	/Nicholas Smith/	Date Considered	06/14/2006
--------------------	------------------	-----------------	------------